



## PRODUCT DATA SHEET



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**Datasheet**



**Resources**

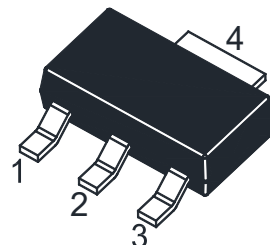


**Samples**

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at [www.jg-semi.cn](http://www.jg-semi.cn). Please email any questions regarding the system integration to [JINGAO\\_questions@jgsemi.com](mailto:JINGAO_questions@jgsemi.com).

### Features

- Halogen and Antimony Free(HAF),  
RoHS compliant



1.Base 2.Collector 3.Emitter 4.Collector

SOT-223 Plastic Package

### Absolute Maximum Ratings ( $T_a = 25^{\circ}\text{C}$ )

Parameter	Symbol	Value	Unit
Collector Base Voltage	$V_{CBO}$	180	V
Collector Emitter Voltage	$V_{CEO}$	150	V
Emitter Base Voltage	$V_{EBO}$	7	V
Collector Current	$I_C$	2	A
Peak Collector Current, Pulsed	$I_{CM}$	3	A
Total Power Dissipation	$P_D$	2 <sup>1)</sup>	W
Total Power Dissipation	$P_D$	3 <sup>2)</sup>	W
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	- 55 to + 150	$^{\circ}\text{C}$

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	62.5 <sup>1)</sup> 41.7 <sup>2)</sup>	$^{\circ}\text{C/W}$

<sup>1)</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.

<sup>2)</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with 2-inch square copper plate in still air.

**Characteristics at  $T_a = 25^\circ\text{C}$  unless otherwise specified**

Parameter	Symbol	Min.	Typ.	Max.	Unit
DC Current Gain					
at $V_{CE} = 5\text{ V}$ , $I_C = 10\text{ mA}$	$h_{FE}$	50	-	-	-
at $V_{CE} = 5\text{ V}$ , $I_C = 500\text{ mA}$	$h_{FE}$	50	-	300	-
at $V_{CE} = 5\text{ V}$ , $I_C = 1\text{ A}$	$h_{FE}$	20	-	-	-
Collector Base Cutoff Current at $V_{CB} = 125\text{ V}$	$I_{CBO}$	-	-	100	nA
Emitter Base Cutoff Current at $V_{EB} = 5.6\text{ V}$	$I_{EBO}$	-	-	100	nA
Collector Base Breakdown Voltage at $I_C = 100\text{ }\mu\text{A}$	$V_{(BR)CBO}$	180	-	-	V
Collector Emitter Breakdown Voltage at $I_C = 10\text{ mA}$	$V_{(BR)CEO}$	150	-	-	V
Emitter Base Breakdown Voltage at $I_E = 100\text{ }\mu\text{A}$	$V_{(BR)EBO}$	7	-	-	V
Collector Emitter Saturation Voltage at $I_C = 500\text{ mA}$ , $I_B = 50\text{ mA}$	$V_{CE(sat)}$	-	-	500	mV
at $I_C = 2\text{ A}$ , $I_B = 200\text{ mA}$		-	-	500	
Base Emitter Saturation Voltage at $I_C = 500\text{ mA}$ , $I_B = 50\text{ mA}$	$V_{BE(sat)}$	-	-	1.1	V
Base Emitter On Voltage at $I_C = 500\text{ mA}$ , $V_{CE} = 5\text{ V}$	$V_{BE(on)}$	-	-	1	V
Transition Frequency at $V_{CE} = 20\text{ V}$ , $I_C = 10\text{ mA}$ , $f = 20\text{ MHz}$	$f_T$	30	-	-	MHz
Collector Output Capacitance at $V_{CB} = 10\text{ V}$ , $f = 1\text{ MHz}$	$C_{ob}$	-	-	20	pF

## Electrical Characteristics Curves

Fig. 1 Output Characteristics Curve

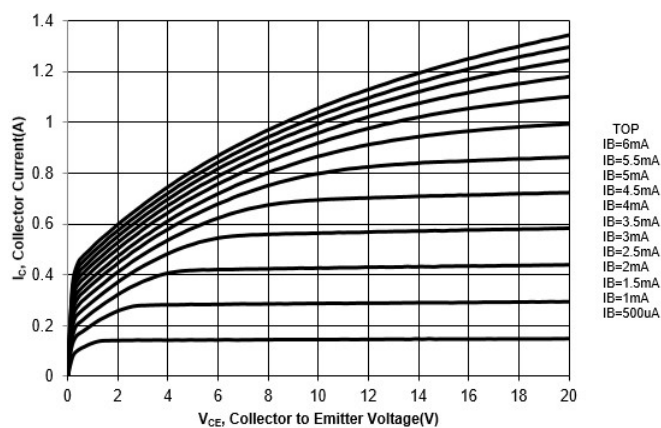


Fig. 2 Collector Current vs. Base to Emitter Voltage

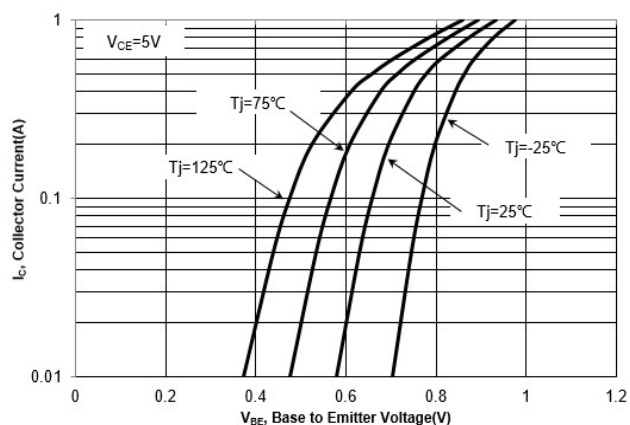


Fig. 3  $h_{FE}$ , DC Current Gain vs. Collector Current

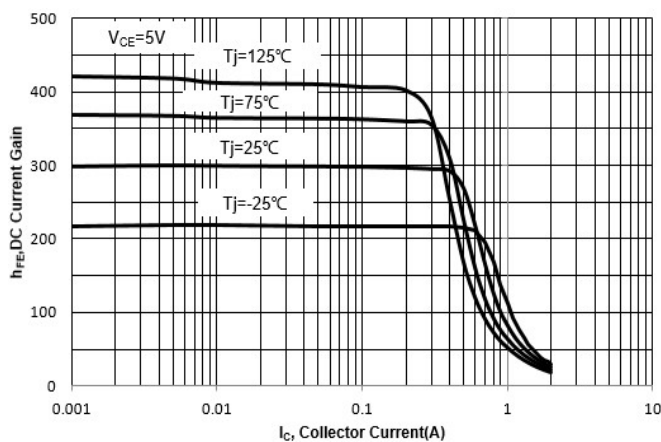
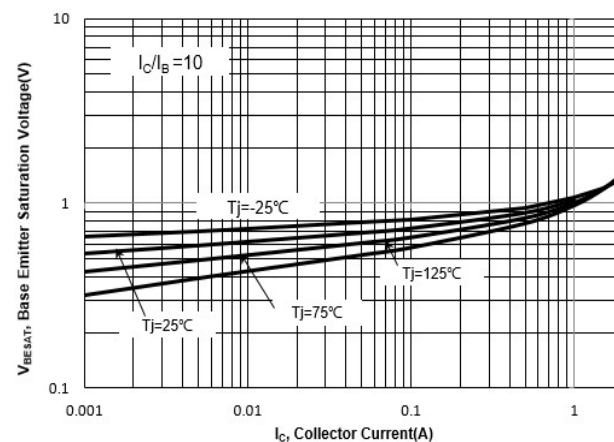


Fig. 4  $V_{BESAT}$  vs. Collector Current



## Electrical Characteristics Curves

Fig. 5  $V_{CESAT}$  vs. Collector Current

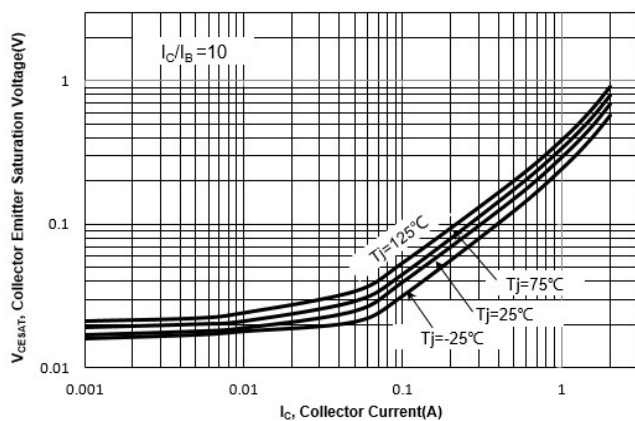


Fig. 6 Output Capacitance

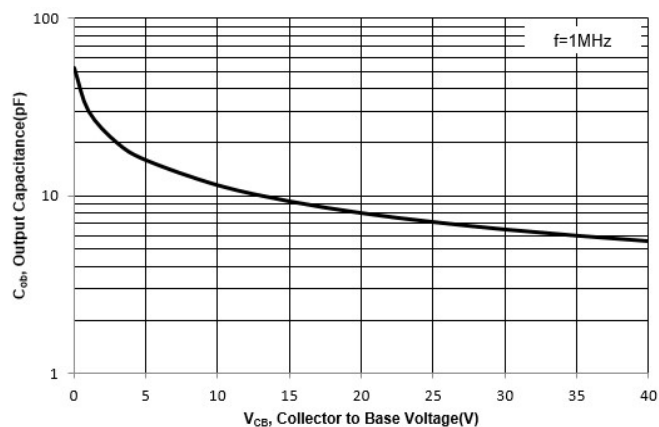
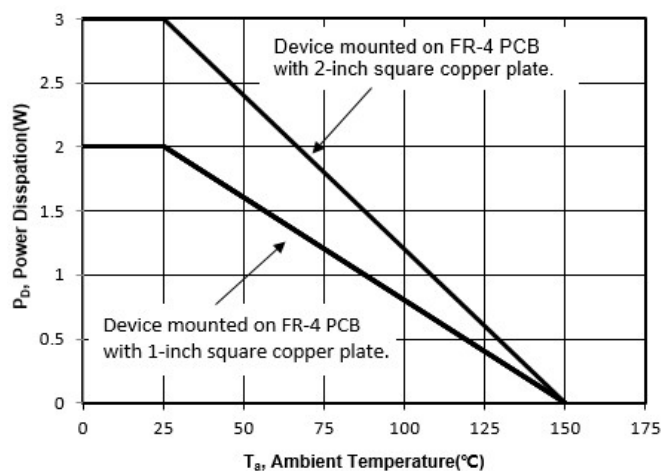
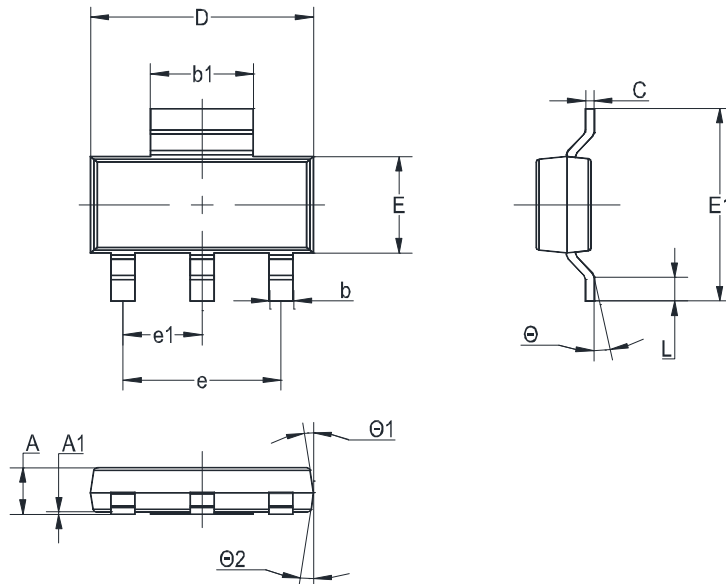
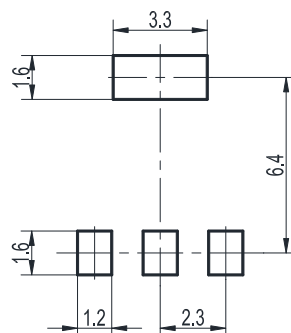


Fig. 7 Power Derating Curve



**Package Outline (Dimensions in mm)**
**SOT-223**


Unit	A	A1	b	b1	C	D	E	E1	e	e1	L	Θ	Θ1	Θ2
mm	1.8	0.1	0.8	3.1	0.32	6.7	3.7	7.3	4.6	2.3	1.1	10°	7°	7°
	1.5	MAX	0.6	2.9	0.22	6.3	3.3	6.7	TYP	TYP	0.7	0°	0°	0°

**Recommended Soldering Footprint**


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